

Product Summary

$V_{(BR)DSS}$	$R_{DS(on) \max}$	I_D $T_C = +25^\circ C$
100V	80m Ω @ $V_{GS} = 10V$	17A
	99m Ω @ $V_{GS} = 6V$	15A

Description

This new generation complementary MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Applications

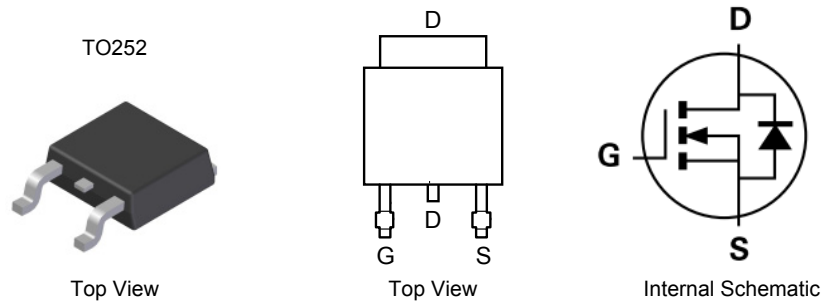
- Power Management Functions
- DC-DC Converters

Features

- Low $R_{DS(ON)}$ – ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- **Lead-Free Finish; RoHS compliant (Note 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Copper leadframe
Solderable per MIL-STD-202, Method 208 $\text{\textcircled{E}}$
- Weight: 0.33 grams (approximate)

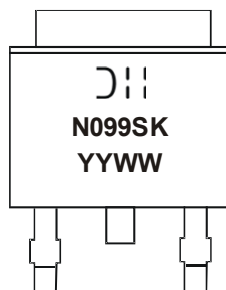


Ordering Information (Note 4)

Part Number	Case	Packaging
DMN10H099SK3-13	TO252	2,500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



$\text{D}|||$ = Manufacturer's Marking
 N099SK = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Digit of Year (ex: 14 = 2014)
 WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	V _{DSS}	100	V	
Gate-Source Voltage	V _{GSS}	±20	V	
Continuous Drain Current (Note 5) V _{GS} = 10V	I _D	T _C = +25°C	17	A
		T _C = +70°C	13	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	20	A	
Avalanche Current, L = 1mH	I _{AS}	7.5	A	
Avalanche Energy, L = 1mH	E _{AS}	28.5	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)	P _D	T _C = +25°C	34	W
		T _C = +70°C	22	
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	51	°C/W	
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	3.6		
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	V _{GS} = 0V, I _D = 250µA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	µA	V _{DS} = 80V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	1.5	2	3	V	V _{DS} = V _{GS} , I _D = 250µA
Static Drain-Source On-Resistance	R _{DS(on)}	—	67	80	mΩ	V _{GS} = 10V, I _D = 3.3A
		—	69	99		V _{GS} = 6V, I _D = 3A
Diode Forward Voltage	V _{SD}	—	0.77	—	V	V _{GS} = 0V, I _S = 3.2A
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C _{iss}	—	1172	—	pF	V _{DS} = 50V, V _{GS} = 0V, f = 1MHz
Output Capacitance	C _{oss}	—	40.8	—		
Reverse Transfer Capacitance	C _{rss}	—	31.3	—		
Gate Resistance	R _G	—	1.6	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = 10V)	Q _g	—	25.2	—	nC	V _{DS} = 50V, I _D = 3.3A
Total Gate Charge (V _{GS} = 4.5V)	Q _g	—	12.2	—		
Gate-Source Charge	Q _{gs}	—	5.3	—		
Gate-Drain Charge	Q _{gd}	—	5.9	—		
Turn-On Delay Time	t _{D(on)}	—	5.4	—	ns	V _{DD} = 50V, R _G = 6.0Ω, I _D = 3.3A
Turn-On Rise Time	t _r	—	5.9	—		
Turn-Off Delay Time	t _{D(off)}	—	20	—		
Turn-Off Fall Time	t _f	—	7.3	—		
Body Diode Reverse Recovery Time	t _{rr}	—	19.7	—	ns	I _F = 3.3A, dI/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{rr}	—	15.9	—	nC	

- Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
6. Guaranteed by design. Not subject to product testing.
7. Short duration pulse test used to minimize self-heating effect.

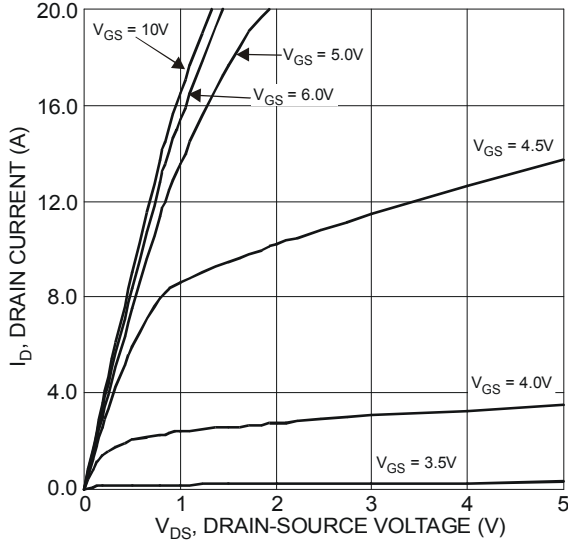


Figure 1 Typical Output Characteristics

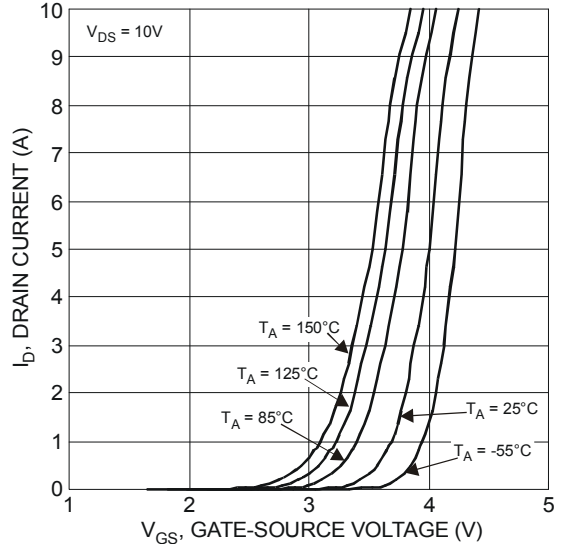


Figure 2 Typical Transfer Characteristics

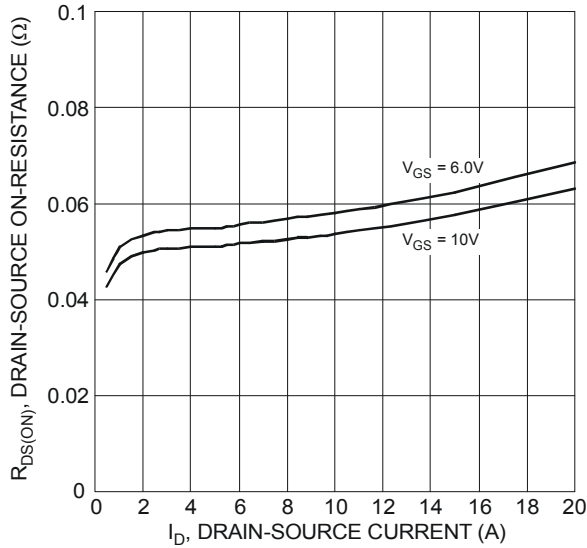


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

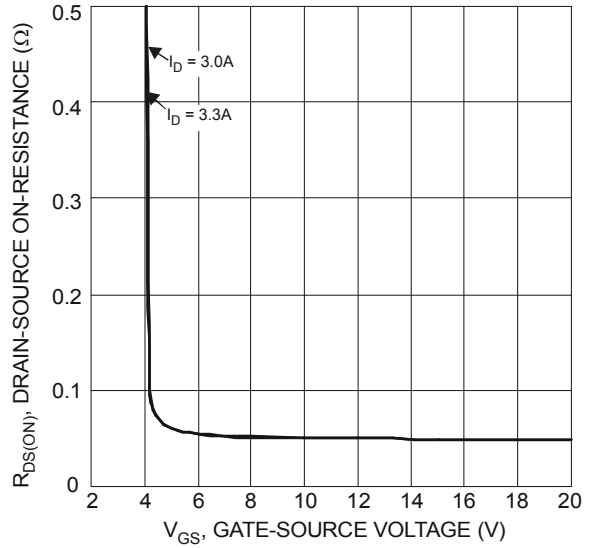


Figure 4 Typical Transfer Characteristics

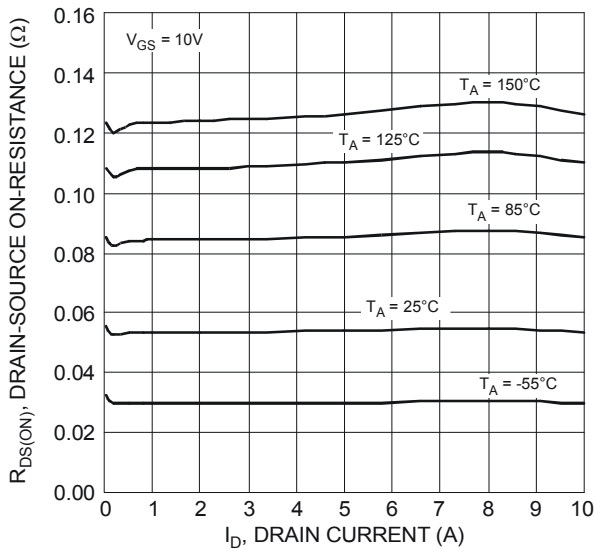


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

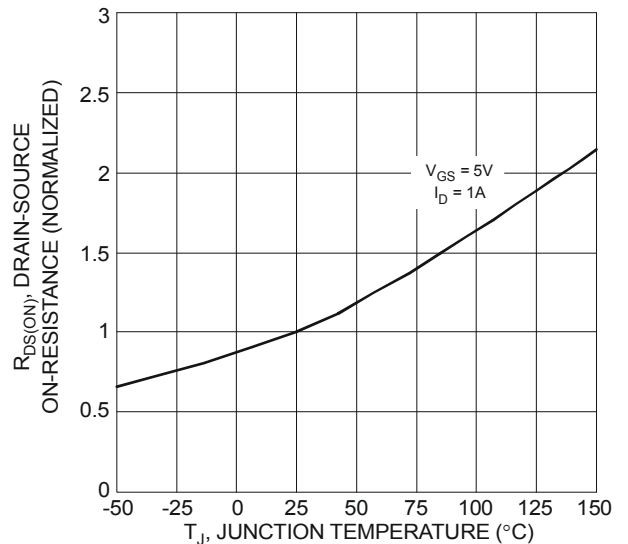


Figure 6 On-Resistance Variation with Temperature

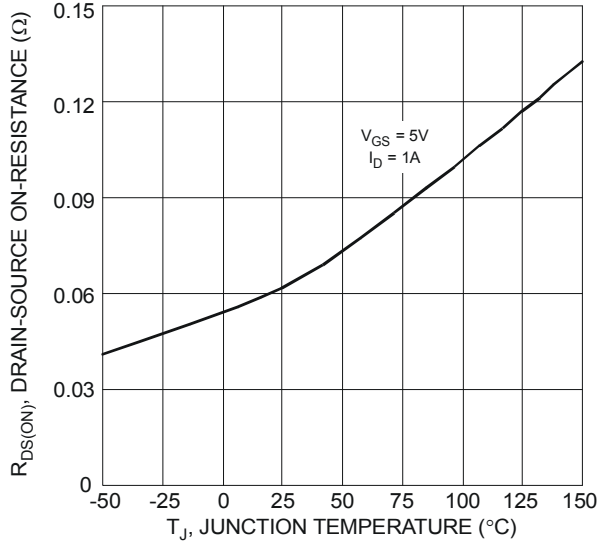


Figure 7 On-Resistance Variation with Temperature

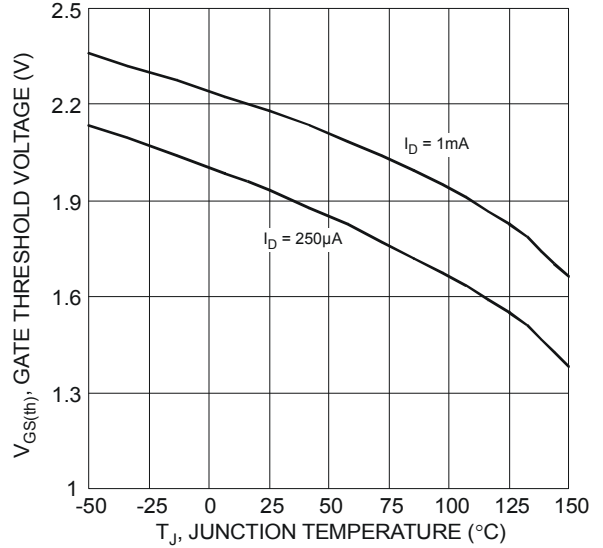


Figure 8 Gate Threshold Variation vs. Ambient Temperature

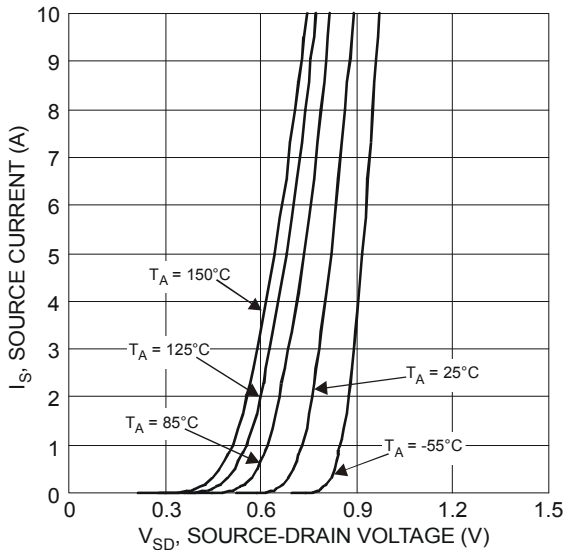


Figure 9 Diode Forward Voltage vs. Current

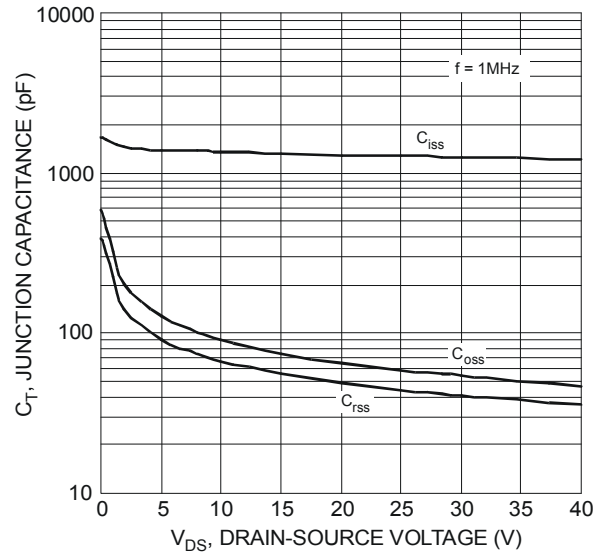


Figure 10 Typical Junction Capacitance

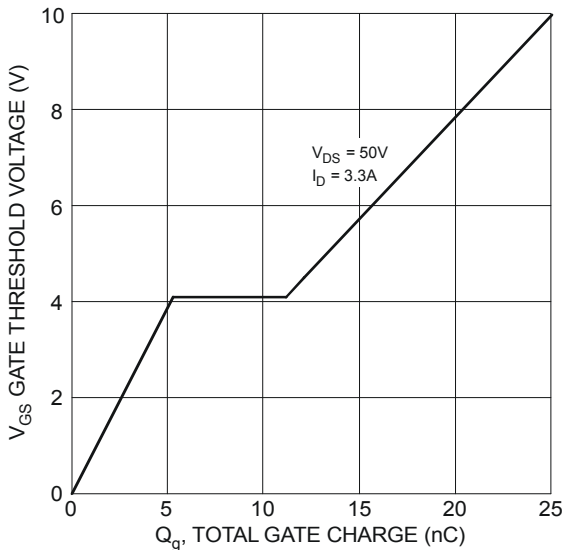


Figure 11 Gate Charge

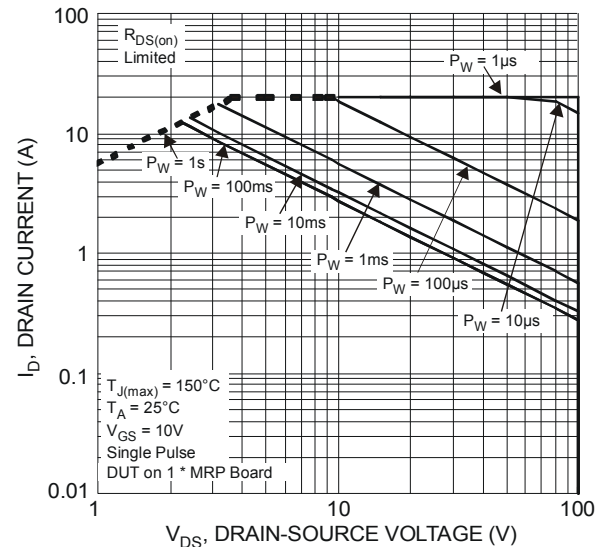
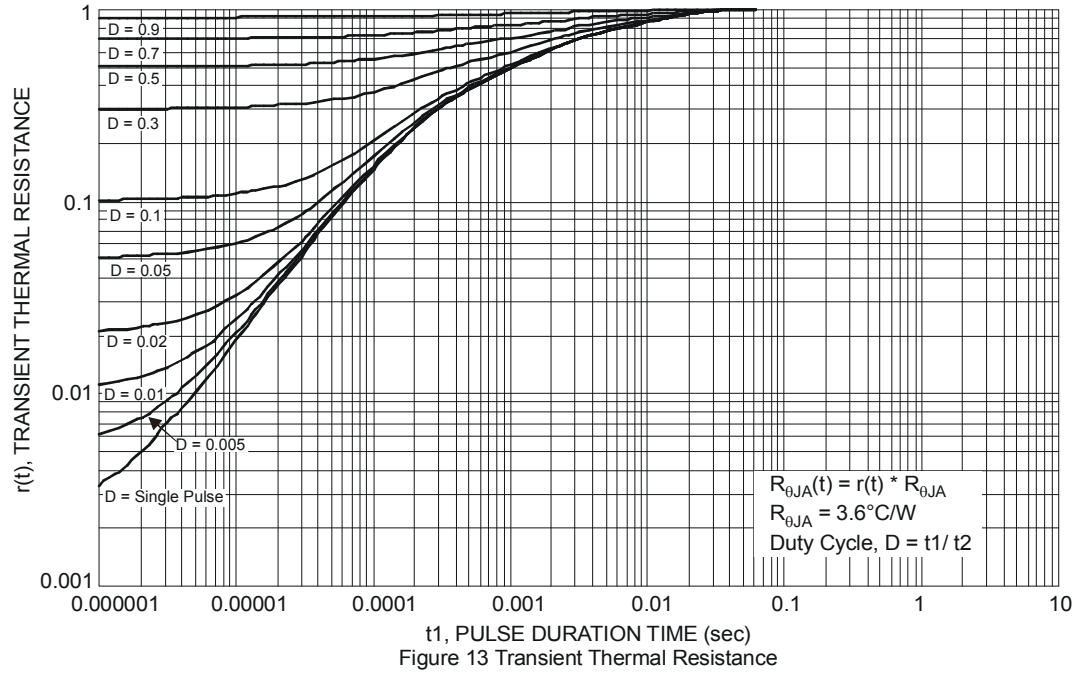
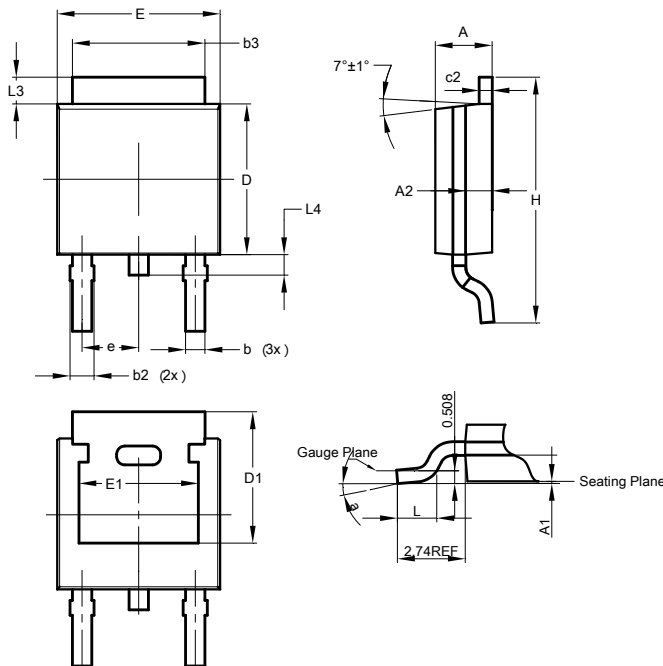


Figure 12 SOA, Safe Operation Area



Package Outline Dimensions

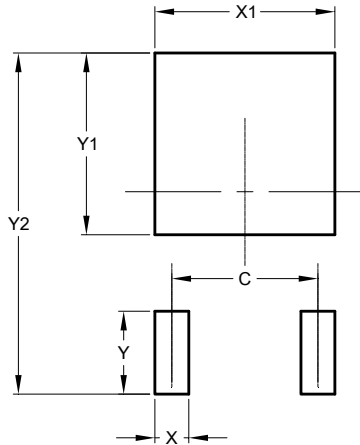
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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